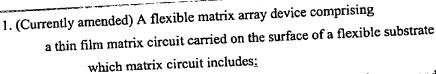
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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:



semiconductor devices arranged in a regular array and occupying respective, discrete, first areas of the substrate, and pixel electrodes correspondingly coupled to each of the

semiconductor devices and occupying respective second areas of the substrate;

wherein

selected regions of the substrate away from the areas occupied by the semiconductor devices comprise areas of weakness at which the substrate is configured such that flexing of the substrate occurs more readily at the second areas than at the first areas.

2. (Currently amended) A curved matrix array device comprising a thin film matrix circuit carried on the surface of a substrate which matrix circuit includes:

semiconductor devices arranged in a regular array and occupying respective, discrete, first areas of the substrate, and

pixel electrodes correspondingly coupled to each of the semiconductor devices and occupying respective second areas of the substrate;

wherein

the substrate is configured such that comprises areas of weakness at selected regions away from the semiconductor devices and

the curvature of the device is accommodated substantially by deformation at the substrate at those regions the second areas.





3. (Currently amended) A device according to Claim 1, wherein the second areas of weakness-comprise locally thinner regions of the substrate.



- 4. (Original) A device according to Claim 3, wherein the locally thinner regions are formed by selective etching of the substrate.
- 5. (Original) A device according to Claim 3, wherein the substrate comprises a laminated structure with at least two layers and in which one layer is patterned to form the locally thinner regions.

- 6. (Currently amended) A device according to Claim 1, wherein the second areas of weakness comprise areas of the substrate at which the material of the substrate is rendered less stiff compared with the first areas of the substrate occupied by the semiconductor devices.
- 7. (Currently amended) A device according to any one of Claims Claim 1, wherein the substrate comprises polymer material.
- 8. (Currently amended) A device according to any one of Claims Claim 1, wherein the second areas of weakness extend as include lines of weakness that facilitate flexing of the substrate between the first areas of the substrate earrying the semiconductor devices.



9. (Currently amended) A device according to Claim 8, wherein the semiconductor devices are arranged in an array of rows and columns and wherein

the second areas of weakness comprise lines of weakness that facilitate flexing of the substrate extending across the array between rows and/or columns of semiconductor devices.







10. (Currently amended) A device according to any one of Claims Claim 1, wherein the discrete-first areas of the substrate carrying the semiconductor devices are thicker than the remaining second areas of substrate.

- 11. (Previously amended) A device according to claim 1, wherein the semiconductor devices each comprise a semiconductor film formed into an island.
- 12. (Previously amended) A device according to claim 1, wherein the semiconductor devices comprises thin film transistors.

13. (Currently amended) A device according to claim 1, wherein the device comprises

an active matrix display devices having an array of display pixels and in which each semiconductor device is connected to a respective pixel electrode earried on the substrate.

14. (Original) A device according to Claim 13, wherein the device comprises

an active matrix liquid crystal display device which includes a further flexible substrate mounted to the substrate carrying the matrix circuit with liquid crystal material disposed between the substrates.

15. (Currently amended) A device according to Claim 14, wherein the further substrate has lines of weaknessthat facilitate flexing formed therein.